HOMEWORK 4. Due: Friday, April 19, 2019.

## This is an individual assignment!

## 1. Extracting and simulating the synthesized design.

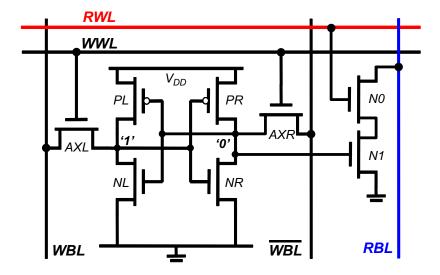
In the first lab, we have created a design by using a strictly digital ('VLSI') design flow. Then in the second lab, we extracted and simulated the synthesized design using custom design tools. In this third lab we will close the loop and build the remaining part of the flow where we will characterize a custom cell for use in the synthesis flow.

To do this, please work through the tutorial entitled: *Introduction to the Custom Design Flow: Building a standard cell*, then turn in:

- a) Using a Monte Carlo simulation of 300 points, plot the mean and sigma for the inputrising/output-fall delay of INVX0\\_RVT (10ps input slope, 1fF load) for VDD between 0.2 and 1 on the same plot. Then plot  $\sigma/\mu$  vs. VDD on another plot. Lastly, plot the delay of a  $6\sigma$  cell relative to the mean vs. VDD on a third plot. Explain conceptually why variation has more of an effect at low voltages.
- b) Generate a histogram of the delay at 0.6V and at 1.05V and try to fit a normal curve (use histfit in Matlab). Are either of them Gaussian? If a distribution is asymmetric, explain why one side has the long tail and not the other. (Optional: use the qqplot command to compare two vectors: one vector from your simulations, and the other sampled from a normal distribution with the  $\mu$  and  $\sigma$  found from the fit using normrnd)
- c) Compute  $\sigma_{Vth}$  for the NMOS in INVX0\\_RVT. Then, using Ion from the alpha-power-law model (K=1.7e-4, Vth=0.366, alpha=1.36), write out the equation for the delay of an inverter (simply assuming maximum current for a transition from VDD to VDD/2 is close enough:  $\Delta T = C\Delta V/I$ , where  $\Delta V = VDD/2$  and C is approximately 1.5fF). Then use Matlab to run a Monte Carlo simulation on this model for 0.6V and 1.05V by using normrnd with a  $\mu$ =0 and  $\sigma$ = $\sigma_{Vth}$  and adding this value to the threshold (which is exactly what HSPICE is doing for Monte Carlo simulation, but HSPICE is solving more complex equations). How do the distributions compare to part b)? Based on the equation you wrote, should the delay be Gaussian?

#### 2. SRAM

Consider an 8-T SRAM cell, shown in figure, which attempts to resolve the contention between the read stability and writeability that appears in the 6-T cell. The cell is operated in a conventional manner within an array.



How do the following parameters affect the characteristics of the array:

- a) How does increased RWL voltage affect the read stability of the cell?
- b) How does increased RWL voltage affect the read access time of the cell?
- c) How does increased WWL voltage affect the writeability of the cell?
- d) How does shortened RWL pulse affect the read stability of the cell?
- e) How does shortened WWL pulse affect the writeability of the cell?
- f) How does negative WBL voltage affect writeability of the cell
- g) How does dereased cell supply voltage (without changing other signal levels) affect the writeability of the cell?

Please explain your answers!

### 3. SRAM redundancy and ECC

We would like to investigate impact of variations on SRAM yield. Assume that read and write margins for the cells vary as Gaussian random variables with an average value of  $\mu$  and a standard deviation of  $\sigma$ . The large array that needs to be put together consists of subarrays with 128 columns and 128 rows.

- a) We would like to design a 24MByte array with no redundancy and a 90% yield. What should be the value of  $\mu/\sigma$  for each of the cells to achieve this yield?
- b) What is the  $\mu/\sigma$  for the sense amplifiers needed to attain this yield? You can assume that cell and sense amp failures are independent.
- c) What amount of redundancy (as a percentage of columns added per array) is needed to improve the parametric yield to 95% when designing an array from a)? Redundant columns are enabled through fuses during chip testing.
- d) For comparison purposes, design an error correction code (may want to search some literature) that corrects for one error per wordline and detects two errors. What is the overhead of such a scheme? If error correction is being used instead of redundancy to correct for bit faults, and applied on the original design with a 90% yield what would be the final yield?

# 4. Power-performance tradeoffs.

- a) Using the alpha-power law model, derive the analytical expression for the energy/delay sensitivity of a design to scaling of a supply voltage. Evaluate this expression at the nominal supply voltage, using the results from Homework 1 (K = 0.001,  $\alpha = 1.6$ ,  $V_{TH} = 0.45$ V, for NMOS)
- b) What is the energy/delay sensitivity of a design to the logic depth? You can define the logic depth as a number of FO4 inverters that fit into one clock period.